電子材料向け多核フェノール

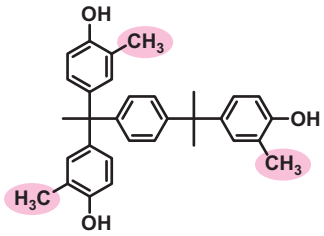
開発品

Polyphenol for electronic materials

電子材料用途を志向した多様な骨格の多核フェノールを開発しています。

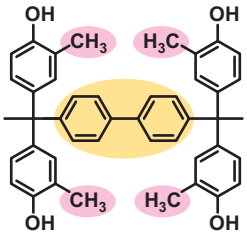
We develop polyphenol with diverse structures for electronic materials.

製品 Products



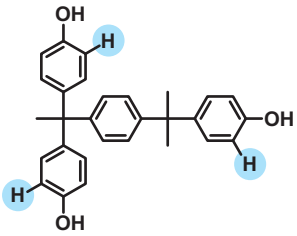
TrisOC-PA

開発品



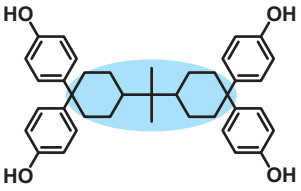
TekOC-DABP

開発品



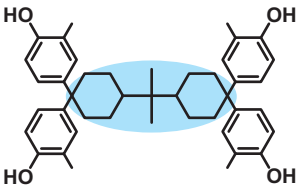
TrisP-PA

既存品



TekP-4HBPA

既存品



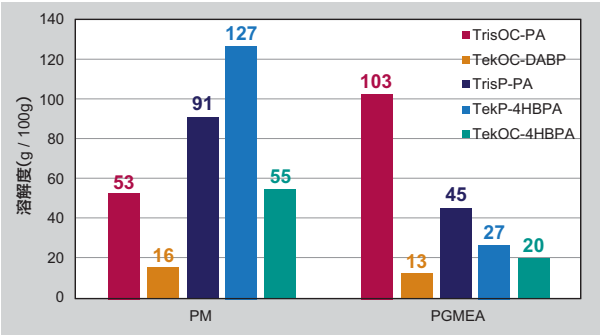
TekOC-4HBPA

既存品

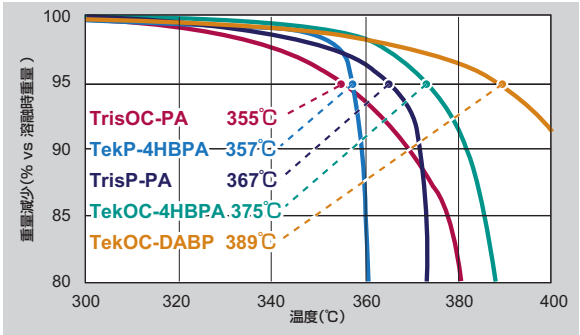
- メチル基 $-CH_3$ 導入による高溶解性・高安定性
  Introducing methyl groups results in high solubility and stability.
- 剛直なビフェニル骨格 導入による高耐熱性
  Introducing biphenyl moiety results in high heat resistant.

物性 Properties

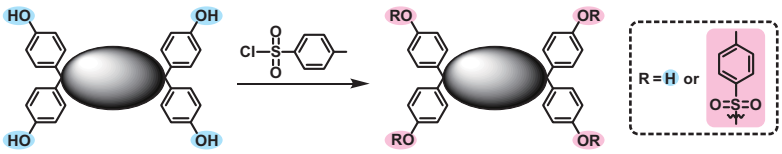
溶解性 Solubility



耐熱性 Heat resistant



スルホニルエステル溶解性 Solubility of sulfonyl esters



Test conditions

Each sulfonyl ester was filtered after dissolving in PM or PGMEA. The resulting solution was stored for 14 days under -18℃. After storage, we checked the presence of precipitation.

Polyphenols	TrisOC-PA	TekOC-DABP	TrisP-PA	TekP-4HBPA	TekOC-4HBPA
Ester conv. rate	88%	83%	89%	81%	81%
Test conc.	Results of dissolution test (PM / PGMEA)				
10%	◎ / ◎	× / ◎	× / ◎	◎ / ◎	◎ / ◎
25%	◎ / ◎	× / ◎	× / ×	◎ / ◎	◎ / ◎
40%	◎ / ◎	× / ◎	× / ×	◎ / ◎	◎ / ◎

◎：析出なし good miscibility even at -18℃　×：析出あり observed precipitation